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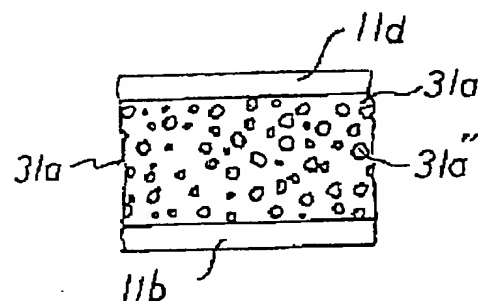
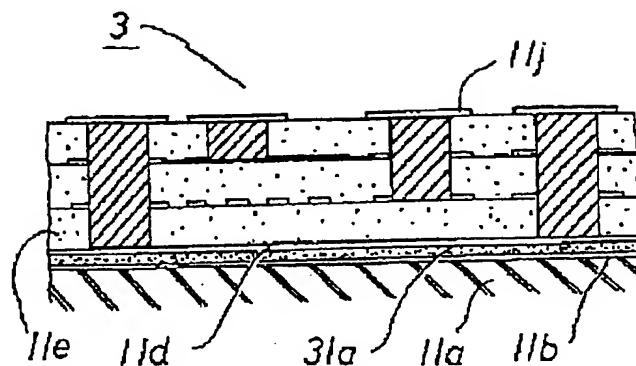
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TITLE : THIN FILM MULTILAYER PRINTED
CIRCUIT BOARD WITH BUILT-IN
CAPACITOR



ABSTRACT : PURPOSE: To increase the manufacturing productivity of a multilayer thin film printed circuit boards with built-in capacitors by forming easily and efficiently capacitors with large capacitances and a small number of defects without having to use any special thin film growth equipment.

CONSTITUTION: A thin film multilayer printed circuit board with built-in capacitors for mounting electronic components on it is prepared by forming on one side of the insulating plate 11a to serve as the base successively from the insulating plate side a ground layer 11b, a thin film dielectric material layer, a power supply layer 11d, and a resin insulating layer 11e, and further forming on top of the resin insulating layer several alternate layers of signal line layers and resin insulating layers with the same material of the resin insulating layer 11e, and finally forming an electrode pad 11j in the exposed surface of the topmost resin insulating layer. Therefore, the thin film dielectric material layer within the capacitors formed by the ground layer, the thin film dielectric material layer, and the power supply layer is formed by the organic resin material 31a' which is obtained by mixing the resin forming the resin insulating layer 11e with the powder 31a'' of a dielectric material.

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